

## 30V N-Channel Enhancement Mode MOSFET

### Description

The SX50N03S uses advanced trench technology to provide excellent Rds(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = 30V I<sub>D</sub> =50 A

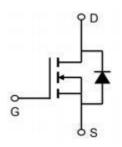
 $R_{DS(ON)} < 6m\Omega$  @  $V_{GS}=10V$ 

### **Application**

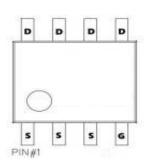
Battery protection

Load switch

Uninterruptible power supply







## Electrical Characteristics (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units V	
Vos	Drain-Source Voltage	30		
Vgs	Gate-Source Voltage ±20		V	
lo@Ta=25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	10V <sup>1</sup> 50		
lo@Ta=70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	s @ 10V <sup>1</sup> 10		
Іом	Pulsed Drain Current <sup>2</sup>	65		
EAS	Single Pulse Avalanche Energy <sup>3</sup>	Single Pulse Avalanche Energy³ 105.8		
las	Avalanche Current	46	А	
PD@Ta=25°C	Total Power Dissipation <sup>4</sup>	1.5	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	mperature Range -55 to 150		
Reja	Thermal Resistance Junction-ambient <sup>1</sup>		°C/W	
Rejc	Thermal Resistance Junction-Case <sup>1</sup> 25		°C/W	





# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V , Ip=250uA	30			V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.028		V/°C
		Vgs=10V , Ip=12A		5.5	6	
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	Vgs=4.5V , Ip=10A		7.2	9	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.2		2.5	V
$^{\triangle}V$ GS(th)	V <sub>GS(th)</sub> Temperature Coefficient	Vgs=Vds , Id =250uA		-6.16		mV/°C
_		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	•
loss	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
Igss	Gate-Source Leakage Current	VGS=±20V, VDS=0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =12A		47		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7		
Qg	Total Gate Charge (4.5V)			21		
Qgs	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		7		nC
Qgd	Gate-Drain Charge			6.9		
Td(on)	Turn-On Delay Time			9.6		
Tr	Rise Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V ,		8.6		
Td(off)	Turn-Off Delay Time	—Rg=3.3		59		ns
Tf	Fall Time	— lb=10A		15.6		
Ciss	Input Capacitance			2295		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		267		pF
Crss	Reverse Transfer Capacitance			210		
<b>l</b> s	Continuous Source Current <sup>1,5</sup>				13	Α
Ism	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			65	Α
Vsp	Diode Forward Voltage <sup>2</sup>	V <sub>G</sub> s=0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.2	V
trr	Reverse Recovery Time			12		nS
Qrr	Reverse Recovery Charge	IF=10A , dl/dt=100A/μs , T <sub>J</sub> =25°C		4.8		nC

#### Note:

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<sup>1.</sup>The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

<sup>2.</sup>The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%

<sup>3.</sup> The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}$ =25V,  $V_{\text{GS}}$ =10V, L=0.1mH,  $I_{\text{AS}}$ =46A

<sup>4.</sup>The power dissipation is limited by 150°C junction temperature

<sup>5.</sup> The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.





### **Typical Characteristics**

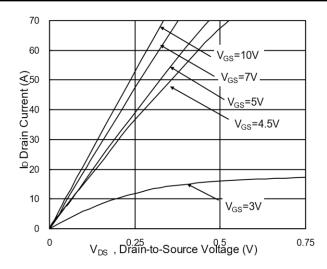


Fig.1 Typical Output Characteristics

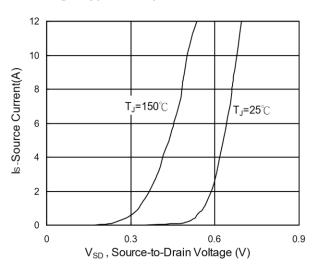
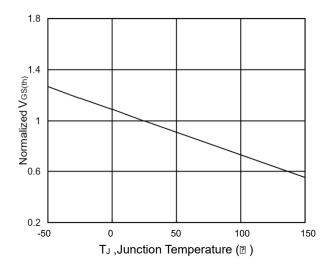


Fig.3 Forward Characteristics of Reverse



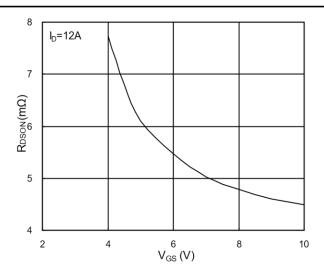


Fig.2 On-Resistance vs. Gate-Source

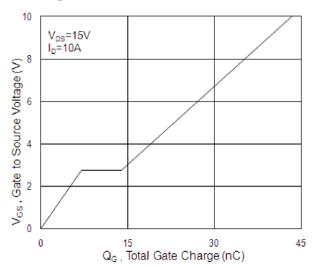
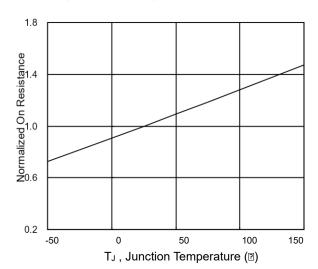


Fig.4 Gate-Charge Characteristics



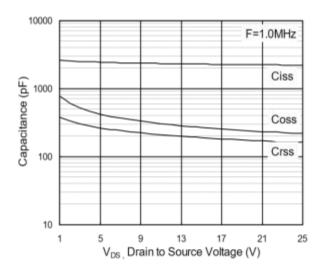
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30V N-Channel Enhancement Mode MOSFET



### **Typical Characteristics**



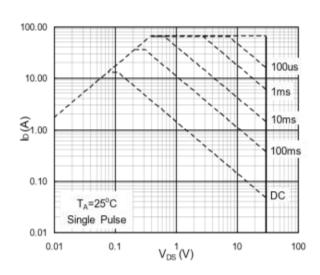


Fig.7 Capacitance

Fig.8 Safe Operating Area

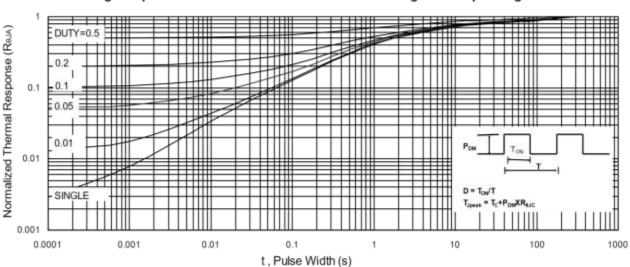


Fig.9 Normalized Maximum Transient Thermal Impedance

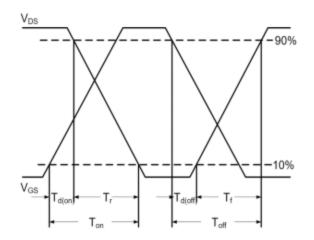


Fig.10 Switching Time Waveform

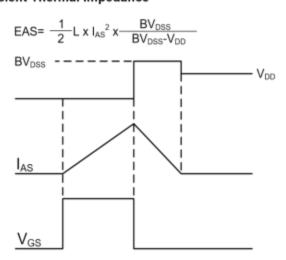
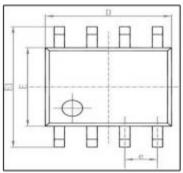
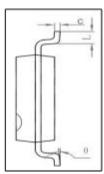


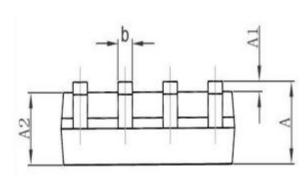
Fig.11 Unclamped Inductive Switching Waveform



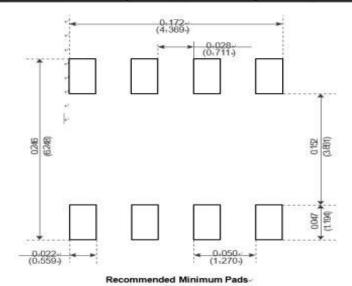
# Package Mechanical Data-SOP-8







Symbol	Dimensions I	n Millimeters	Dimensions	In Inches
	Min	Max	Min	Max
Α	1. 350	1. 750	0. 053	0.069
A1	0.100	0. 250	0.004	0.010
A2	1. 350	1. 550	0. 053	0.061
b	0. 330	0. 510	0.013	0.020
С	0. 170	0. 250	0.006	0.010
D	4. 700	5. 100	0. 185	0.200
E	3. 800	4. 000	0. 150	0. 157
E1	5. 800	6. 200	0. 228	0. 244
е	1. 270 (BSC)		0. 050 (	BSC)
L	0.400	1. 270	0.016	0.050
θ	0°	8°	0°	8°



**Package Marking and Ordering Information** 

Product ID	Pack	Marking	Qty(PCS)		
TAPING	SOP-8		3000		

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